

SOT23-6L Plastic-Encapsulate ESD Protection Diodes

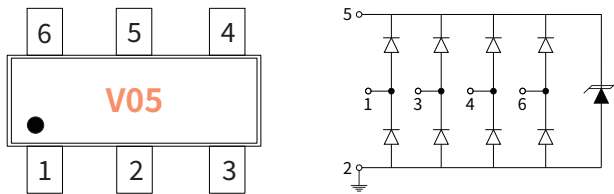
● Features

- Low leakage current
- SOT-23-6L surface mount package
- IEC 61000-4-2 (ESD Air): $\pm 30\text{kV}$
- IEC 61000-4-2 (ESD Contact): $\pm 30\text{kV}$
- IEC 61000-4-5 (Lightning 8/20 μs): 4A

● Applications

- Automotive Applications
- CAN Bus
- Electronic Control Units
- Body Control Units
- ADAS Control Units
- Power Train Control Units

● Function Diagram



Reverse Working Voltage
5.0V Max.

Ultra small capacitance
 $C_{I/O-GND}=1.0\text{pF(Typ.)}$
 $C_{I/O-I/O}=0.5\text{pF(Typ.)}$

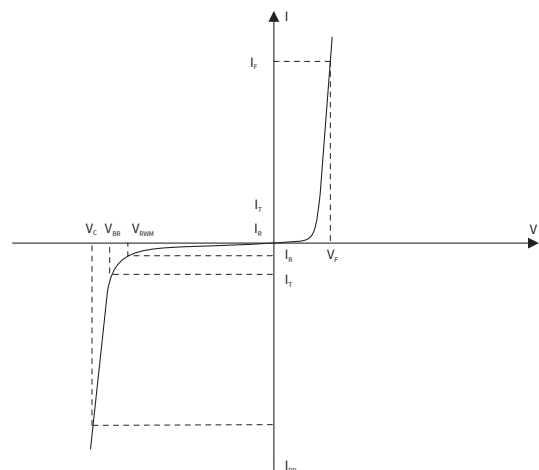


● Maximum Ratings (Ta=25°C Unless otherwise specified)

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
V _{ESD}	Electrostatic Discharge Voltage	ESD per IEC 61000-4-2(Air)	± 30	KV
		ESD per IEC 61000-4-2(Contact)	± 30	KV
P _{PP}	Peak Pulse Power	tp = 8/20 μs	80	W
I _{PP}	Rated Peak Pulse Current	tp = 8/20 μs	4.0	A
T _J	Operating JunctionTemperature Range	—	-55 to +125	°C
T _{STG}	Operating JunctionTemperature Range	—	-55 to +150	°C

● Electrical Parameter

SYMBOL	PARAMETER
V _C	Clamping Voltage @ I _{PP}
V _{BR}	Breakdown Voltage @ I _T
I _{PP}	Peak Pulse Current
I _T	Test Current
I _R	Reverse Leakage Current @ VRWM
V _{RWM}	Peak Reverse Working Voltage
P _{PP}	Peak Pulse Power Dissipation
C _J	Junction Capacitance @ V _R =0V,f=1MHz
I _F	Forward Current
V _F	Forward Voltage @I _F



● **Electrical Characteristics** (Ta=25°C Unless otherwise specified)

PARAMETER	SYMBOL	CONDITION	Min	Typ	Max	UNIT
Peak Reverse Working Voltage	V_{RWM}	$T_a=25^\circ\text{C}$	—	—	5.0	V
Breakdown Voltage	V_{BR}	$I_R=1\text{mA}, T_a=25^\circ\text{C}$	6.0	—	—	V
Reverse Leakage Current	I_R	$V_{RWM}=5.0\text{V}, T_a=25^\circ\text{C}$	—	—	5.0	μA
Forward voltage	V_F	$I_F=10\text{mA}, T_a=25^\circ\text{C}$	—	0.8	1.0	V
Clamping Voltage	V_C	$I_{PP}=4.0\text{A}, t_p=8/20\mu\text{s}$	—	13.5	15	V
Junction Capacitance	C_J	$V_{RWM}=0\text{V}, f=1\text{MHz}, \text{Between I/O pins}$	—	0.5	—	pF
		$V_{RWM}=0\text{V}, f=1\text{MHz}, \text{pin to GND}$	—	1.0	—	

● **Ratings And Characteristics Curves** (Ta=25°C Unless otherwise specified)

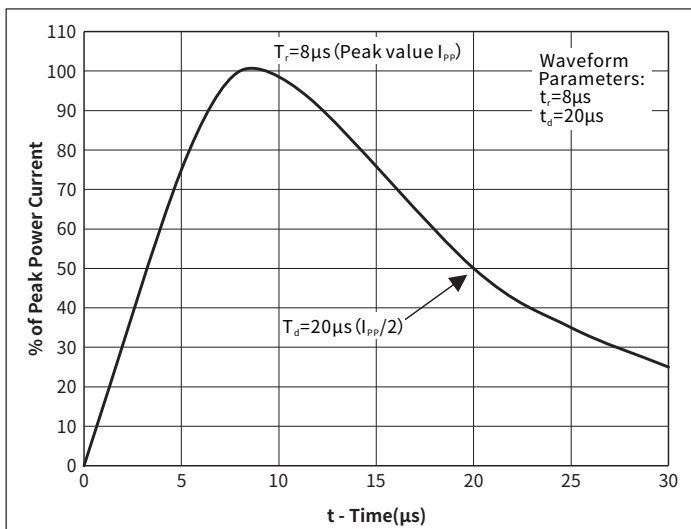


Fig.1 Pulse Waveform

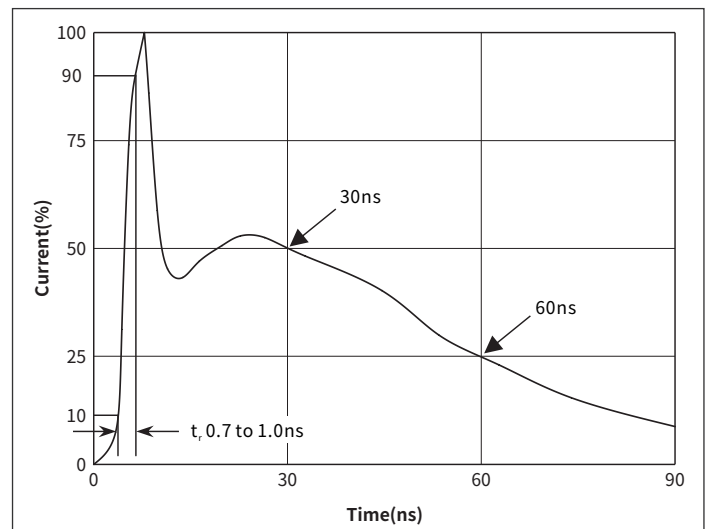


Fig.2 Pulse Waveform-ESD(IEC61000-4-2)

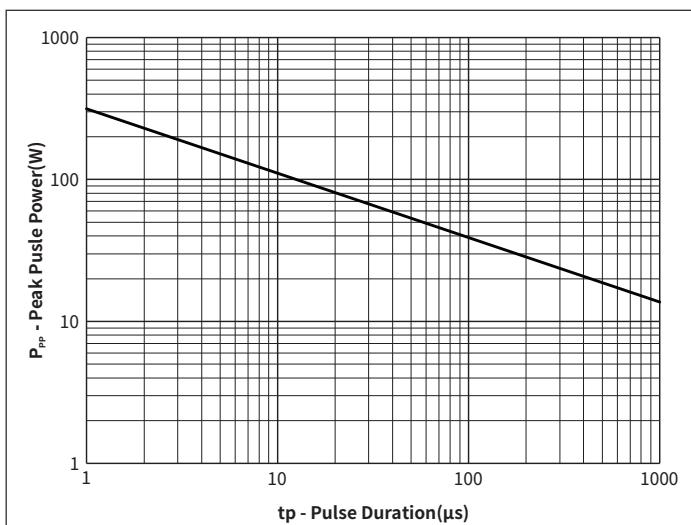


Fig.3 Peak Pulse Power vs. Pulse Time

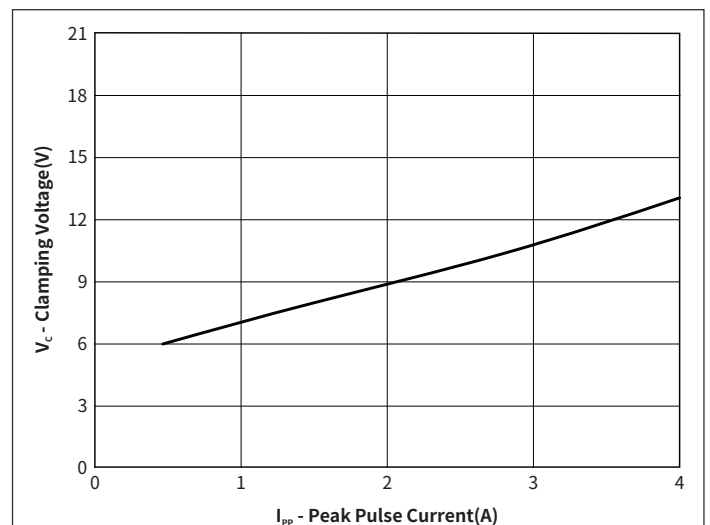
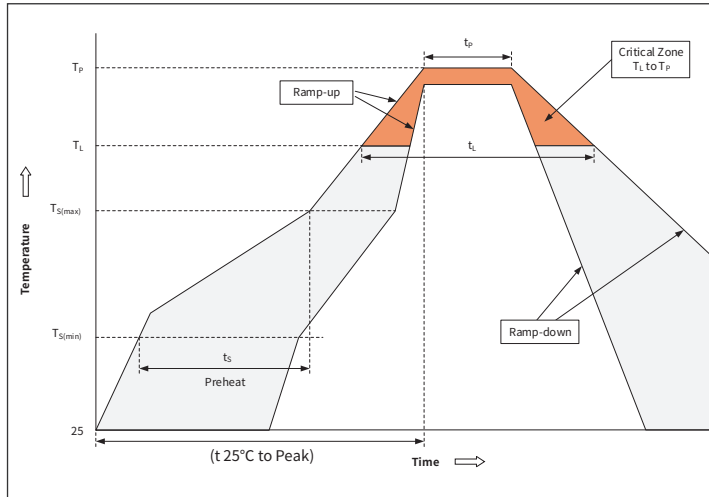


Fig.4 Clamping Voltage vs. Peak Pulse Current

Ordering Information

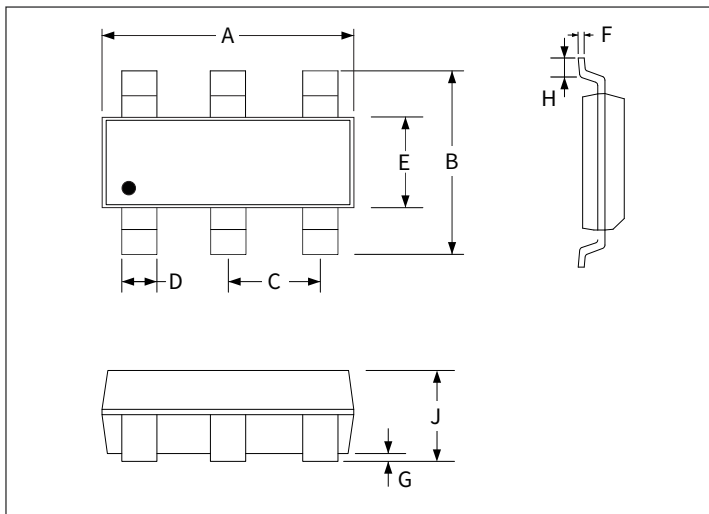
PACKAGE	PACKAGE CODE	UNIT WEIGHT(g)	REEL(pcs)	BOX(pcs)	CARTON(pcs)	DELIVERY MODE
SOT-23-6L	R1	0.008	3000	30000	120000	7"

Recommended Soldering Conditions



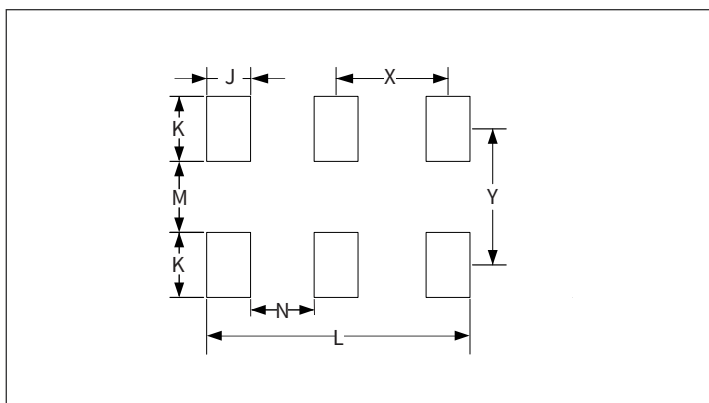
Profile Feature		Pb-Free Assembly
Pre-heat	Temperature Min ($T_{S(min)}$)	+150°C
	Temperature Max ($T_{S(max)}$)	+200°C
	Time (Min to Max) (t_s)	60-180 secs.
Average ramp up rate (Liquid us Temp (T_l) to peak)		3°C/sec. Max
$T_{S(max)}$ to T_L - Ramp-up Rate		3°C/sec. Max
Reflow	Temperature (T_l) (Liquid us)	+217°C
	Temperature (t_l)	60-150 secs.
Peak Temp (T_p)		+260(+0/-5)°C
Time within 5°C of actual Peak Temp (t_p)		20-40secs
Ramp-down Rate		6°C/sec. Max
Time 25°C to Peak Temp (T_p)		8 min. Max
Do not exceed		+260°C

Package Outline Dimensions (SOT23-6L)



Symbol	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	2.80	3.00	0.110	0.118
B	2.60	3.00	0.102	0.118
C	0.93	0.97	0.037	0.038
D	0.41		0.016	
E	1.50	1.70	0.059	0.067
F	0.11	0.19	0.004	0.007
G	-	0.10	-	0.004
H	0.40	-	0.016	-
J	1.00	1.20	0.035	0.057

Suggested Pad Layout



Symbol	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
J	0.60	-	0.024	-
K	0.90	-	0.035	-
M	-	1.40	-	0.055
N	-	0.35	-	0.014
X	-	0.95	-	0.037
Y	-	2.30	-	0.090
L	-	2.50	-	0.098

Note :
This soldering footprint is for reference purposes only. Please consult your manufacturing group to ensure your PCB design guidelines are met.